CLAIMS

1. A film for protective film formation which comprises an energy ray-curable compound (B), has properties described below, and is used for forming a protective film on a back surface of a semiconductor wafer or a semiconductor chip, wherein

when a cured product is formed by curing the film for protective film formation by irradiation with energy rays, the cured product has a Young's modulus of at least 500 MPa and an elongation at break of at least 8% but not more than 100%.

2. The film for protective film formation according to Claim 1, wherein within the film for protective film formation, an amount of an energy ray-curable compound (B1) having 2 to 4 energy ray-polymerizable groups within a single molecule, relative to a total mass of the energy ray-curable compound (B), is at least 90% by mass.

3. A composite sheet for protective film formation, comprising the film for protective film formation according to Claim 1 or 2 provided on one surface of a support sheet.